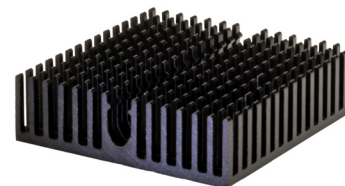


MODEL: HSB36-353510 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- low profile
- aluminum alloy
- black anodized finish



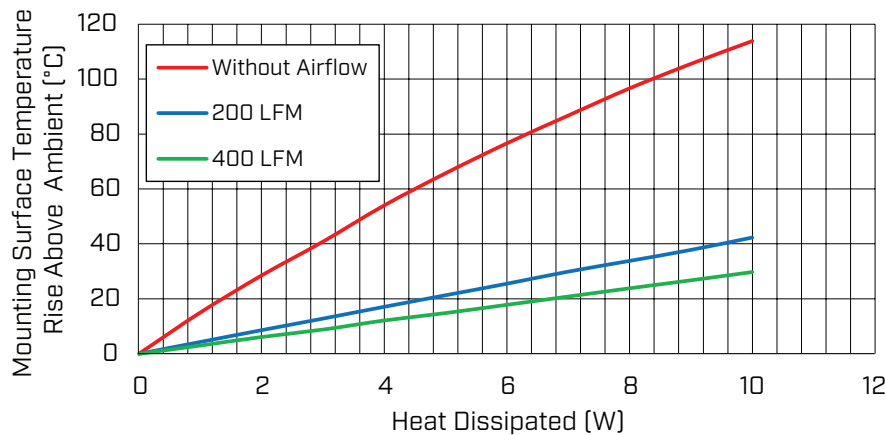
MODEL

HSB36-353510	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT, nat conv [W]
	12.72	15.0	4.3	3.0	5.90

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	15.0	4.3	3.0
2	28.5	8.6	6.1
3	40.8	12.8	8.8
4	54.0	17.1	12.1
5	65.7	21.3	14.8
6	76.6	25.5	17.8
7	86.7	29.9	20.8
8	96.6	33.8	23.8
9	105.5	37.8	26.7
10	113.8	42.3	29.7

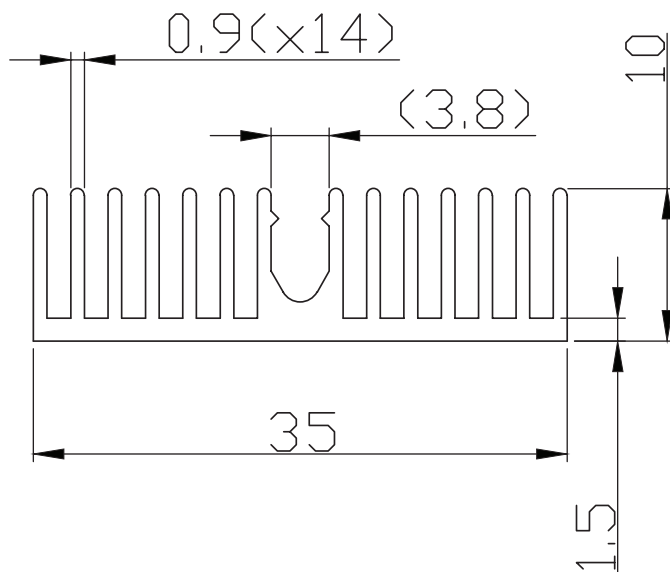
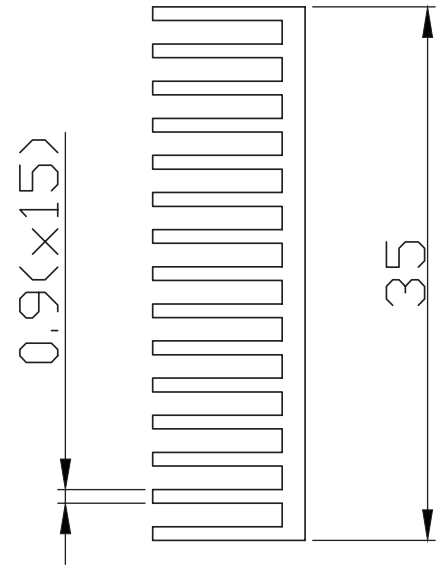
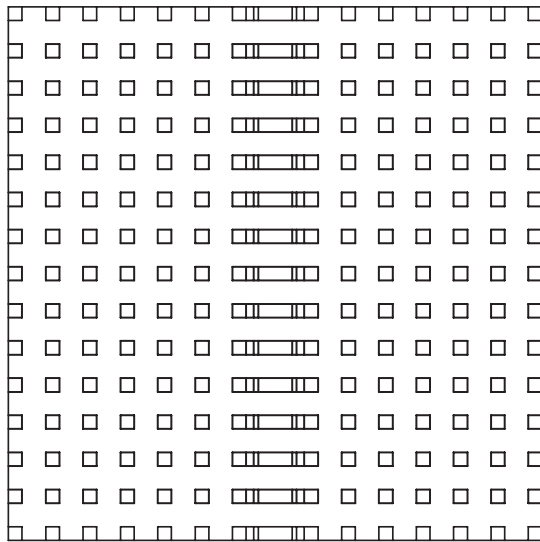


T_{hs}: "hot spot" temperature measured on the heatsink
 T_a: ambient temperature

MECHANICAL DRAWING

units: mm
tolerance: ±0.50 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	11 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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